

Global Display Driver IC Chip-on-Film (COF) Package Modules Market 2026 by Manufacturers, Regions, Type and Application, Forecast to 2032

<https://marketpublishers.com/r/GFA8A3FAFF2DEN.html>

Date: August 2026

Pages: 122

Price: US\$ 3,480.00 (Single User License)

ID: GFA8A3FAFF2DEN

Abstracts

According to our (Global Info Research) latest study, the global Display Driver IC Chip-on-Film (COF) Package Modules market size was valued at US\$ 748 million in 2025 and is forecast to a readjusted size of US\$ 1054 million by 2032 with a CAGR of 5.2% during review period.

Display driver IC chip on film package modules are physical semiconductor packaging components used for driver connection in display panels. The core process is to mount display driver IC chips onto flexible film circuit substrates and complete gold bump connection, inner lead bonding, outer lead connection, encapsulation protection and electrical testing, enabling high density, low impedance and stable transmission of display driver signals between the display panel, the driver IC and the main control circuit. The product mainly covers source driver COF modules, gate driver COF modules, two metal COF modules, fine pitch COF modules, thermally enhanced COF modules and large size display COF modules. Key processes include roll to roll flexible circuit fabrication, wafer gold bumping, chip mounting, thermal compression bonding, encapsulation resin protection, visual inspection and final electrical testing. Key specifications usually include line pitch, lead pitch, film width, copper layer structure, bending reliability, thermal resistance, electrical yield, bonding strength and panel side connection stability. Major applications include LCD televisions, monitors, notebook computers, tablets, automotive displays, OLED displays and high resolution large size display modules. Based on the finished COF package module product scope, the global average industry price of display driver IC COF package modules in 2025 was about USD 0.45 to USD 0.85 per unit, the average industry gross margin was about 24% to 32%, and global shipment volume was about 0.9 to 1.6 billion units.

Display driver IC COF package modules sit in the middle of the display panel value chain. The upstream side includes PI film, copper foil, photo patterning materials, encapsulation resin, gold bumping materials, COF tape substrates and display driver IC wafers. The midstream stage covers COF circuit fabrication, chip mounting, thermal compression bonding, encapsulation protection and final testing. The downstream side serves televisions, monitors, notebook computers, tablets, automotive displays, OLED display modules and other high resolution display products. This product is not a general flexible printed circuit and it is not simply a display driver IC. It is a driver packaging and connection format that enables high density routing, narrow bezel design, stable signal transmission and reliable panel assembly. Demand remains supported by large size high resolution displays, automotive multi display systems and the continued migration of display modules toward thinner and more integrated designs. However, growth is more likely to come from specification upgrades and application mix changes than from a broad surge in end device shipments.

The competitive structure is highly concentrated by region and by process capability. Core supply is mainly built around Taiwan, mainland China and South Korea, while Japan and other regions play a stronger role in materials, flexible substrates and selected upstream processes. The real barrier is not just packaging capacity. It is the combined capability in gold bumping, fine pitch flexible circuits, high precision chip placement, bonding reliability, yield control, panel customer qualification and stable high volume delivery. Some companies focus on display driver IC back end packaging and testing, while others specialize in COF tape substrates and flexible circuit structures. These two groups are closely linked, but they should not be counted under the same revenue boundary without adjustment. Mainland Chinese suppliers have increased investment in display driver packaging, COF tape production and integrated COF IC manufacturing, which is gradually reshaping the supply chain from an externally dependent structure toward a more localized and regionally diversified model.

The policy and capital environment remains supportive because display panels, advanced packaging, semiconductor localization and automotive electronics are all strategic manufacturing priorities in major markets. Investment is moving toward finer pitch COF lines, two metal COF structures, better thermal designs, higher automation in testing and more stable mass production for large size and automotive display applications. The outlook is stable rather than aggressively high growth. COG, COP, panel level integration and new display architectures will continue to take part of the demand in small size and high end devices, but COF still has a clear role where mature processing, cost efficiency, bending tolerance and mass production reliability matter. The industry's future opportunities will come from higher specification products, a more

complete local supply chain, stronger automotive and industrial display adoption, and better process integration between COF substrates, driver IC packaging and panel module assembly.

This report is a detailed and comprehensive analysis for global Display Driver IC Chip-on-Film (COF) Package Modules market. Both quantitative and qualitative analyses are presented by manufacturers, by region & country, by Type and by Application. As the market is constantly changing, this report explores the competition, supply and demand trends, as well as key factors that contribute to its changing demands across many markets. Company profiles and product examples of selected competitors, along with market share estimates of some of the selected leaders for the year 2025, are provided.

Key Features:

Global Display Driver IC Chip-on-Film (COF) Package Modules market size and forecasts, in consumption value (\$ Million), sales quantity (Million Units), and average selling prices (US\$/Unit), 2021-2032

Global Display Driver IC Chip-on-Film (COF) Package Modules market size and forecasts by region and country, in consumption value (\$ Million), sales quantity (Million Units), and average selling prices (US\$/Unit), 2021-2032

Global Display Driver IC Chip-on-Film (COF) Package Modules market size and forecasts, by Type and by Application, in consumption value (\$ Million), sales quantity (Million Units), and average selling prices (US\$/Unit), 2021-2032

Global Display Driver IC Chip-on-Film (COF) Package Modules market shares of main players, shipments in revenue (\$ Million), sales quantity (Million Units), and ASP (US\$/Unit), 2021-2026

The Primary Objectives in This Report Are:

To determine the size of the total market opportunity of global and key countries

To assess the growth potential for Display Driver IC Chip-on-Film (COF) Package Modules

To forecast future growth in each product and end-use market

To assess competitive factors affecting the marketplace

This report profiles key players in the global Display Driver IC Chip-on-Film (COF) Package Modules market based on the following parameters - company overview, sales quantity, revenue, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include Chipbond Technology Corporation, ChipMOS TECHNOLOGIES INC., Hefei Chipmore Technology Co., Ltd., Union Semiconductor (Hefei) Co., Ltd., LB Semicon Inc., Changzhou Xingsheng Semiconductor Technology Co., Ltd., LG Innotek Co., Ltd., STEMCO Co., Ltd., JMC Electronics Co., Ltd., FLEXCEED Co., Ltd., etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Market Segmentation

Display Driver IC Chip-on-Film (COF) Package Modules market is split by Type and by Application. For the period 2021-2032, the growth among segments provides accurate calculations and forecasts for consumption value by Type, and by Application in terms of volume and value. This analysis can help you expand your business by targeting qualified niche markets.

Market segment by Type

Source Driver COF Modules

Gate Driver COF Modules

Combined Driver COF Modules

Others

Market segment by Circuit Metal Structure

One Metal COF Modules

Two Metal COF Modules

Others

Market segment by Lead Pitch

Standard Pitch COF Modules (>30 ?m)

Fine Pitch COF Modules (15?30 ?m)

Super Fine Pitch COF Modules (

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